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		warrant that this design will meet the side normal structure and the side side side side side side side sid	specifications, will be suitable for your application or fit for any particular in is production worthy. You should completely validate and test vour de-	/ information contained therein. Texas Instruments and/or its licensors do no purpose, or will operate in an implementation. Texas Instruments and/or its sign implementation to confirm the system functionality for your application.	Drawn By: Engineer: Jari Nieme	elä	File: LP5922_Design Contact: http://www	01 CoverSheet.SchDoc ti.com/support	Sheet: 1 of 3 Size: B	http://www.ti.com © Texas Instruments 2016
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PCB Number: TIDA-01322 PCB Rev: E1

PCB LOGO Pb-Free Symbol PCB LOGO FCC disclaimer

LBL1 PCB Label Size: 0.65" x 0.20 "

ZZ1 Label Assembly Note This Assembly Note is for PCB labels only

	-
002	ChangeMe!

Variant/Label Table Label Text

ChangeMe!

ZZ2 Assembly Note These assemblies are ESD sensitive, ESD precautions shall be observed.

1

ZZ3 Assembly Note These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

Variant

001

ZZ4 Assembly Note These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

	Orderable:
	TID #: N/A
	Number: TIDA-01322
	SVN Rev: Not in version
	Drawn By:
	Engineer: Jari Niemelä

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 Assembly Variant: 001

 File:
 LP5922_Design_EVM_Hardware.SchDoc

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